



Material Content Data Sheet



Sales Product Name		TDA7210		Issued		28. August 2013		
MA#		MA000527228						
Package		PG-TSSOP-28-1		Weight*		106.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.457	2.30	2.30	22970	22970
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134585	
	non noble metal	iron	7439-89-6	19.882	18.59	32.05	185855	320440
wire	noble metal	gold	7440-57-5	0.938	0.88	0.88	8769	8769
encapsulation	organic material	carbon black	1333-86-4	0.196	0.18		1833	
	plastics	epoxy resin	-	8.301	7.76		77598	
	inorganic material	silicondioxide	60676-86-0	56.867	53.15	61.09	531573	611004
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14391	14391
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13233	13233
glue	plastics	acrylic resin	-	0.197	0.18		1839	
	noble metal	silver	7440-22-4	0.787	0.74	0.92	7354	9193
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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